

**IN THE CLAIMS:**

Please amend the claims as follows.

Claim 1 (Currently Amended): A back-illuminated semiconductor device comprising:  
a semiconductor substrate, having:

a photodetecting unit formed on one surface,

a thinned portion formed by etching a region, opposing the photodetecting unit, of  
another surface,

an outer edge surrounding the thinned portion, and

first electrodes disposed on the one surface at ~~[[an]]~~ the outer edge ~~of the thinned~~  
~~portion~~ and electrically connected to the photodetecting unit;

a wiring substrate, disposed to oppose the one surface side of the semiconductor substrate  
and having second electrodes connected via conductive bumps to the first electrodes; and

a resin, filling a gap between the wiring substrate and the outer edge ~~of the thinned~~  
~~portion to reinforce the strength of bonding of the respective first electrodes and the respective~~  
~~second electrodes~~ with the conductive bumps; and

wherein the resin is a resin sheet ~~that is formed in advance so as to surround a periphery~~  
~~of a gap between the thinned portion and the wiring substrate except for portions of the~~  
~~periphery, and wherein a communicating portion is formed so as to laterally penetrate through~~  
the resin sheet.

Claim 2 (Original): The semiconductor device according to Claim 1, wherein the  
photodetecting unit has a plurality of pixels that are arrayed one-dimensionally or two-

dimensionally.

Claim 3 (Currently Amended): A semiconductor device manufacturing method comprising the steps of:

preparing a semiconductor substrate, having:

a photodetecting unit formed on one surface,

a thinned portion formed by etching a region, opposing the photodetecting unit, of another surface,

an outer edge surrounding the thinned portion, and

first electrodes disposed on the one surface at ~~[[an]]~~ the outer edge ~~of the thinned portion~~ and electrically connected to the photodetecting unit;

preparing a wiring substrate, disposed to oppose the one surface side of the semiconductor substrate and having second electrodes connected via conductive bumps to the first electrodes;

adhering a solid resin sheet onto the outer edge ~~a predetermined region on the other surface~~ of the semiconductor substrate; and

thermocompression bonding the semiconductor substrate, with the resin sheet, to the wiring substrate; and

wherein ~~the predetermined region is set to surround a periphery of a gap between the thinned portion and the wiring substrate except for portions of the periphery~~ a communicating portion is formed so as to laterally penetrate through the resin sheet.